

Agency Contact:
Kenn Durrence
The Hoffman Agency
(408) 975-3097
kdurrence@hoffman.com

Company Contact:
Chris Stai
Advanced Interconnect Technologies
(408) 331-7325
cstai@aitemail.com

**ADVANCED INTERCONNECT TECHNOLOGIES
RECEIVES JEDEC APPROVAL FOR ITS ETCHED LEADLESS PACKAGE**

ELP Offers Superior Design Flexibility, Package Reliability and Faster Time to Market

SINGAPORE, May 14, 2007 – Advanced Interconnect Technologies, a global provider of semiconductor assembly and test services, today announced that it has received approval from the prestigious Joint Electron Device Engineering Council (JEDEC) for its QFN-style Etched Leadless Package (ELP) technology. JEDEC, the semiconductor engineering standardization body of the Electronic Industries Alliance (EIA), a trade association that represents all areas of the electronics industry, approved AIT's Microelectronics Outline document MO-247 and Design Guide 4.19 for ELP.

“Receiving the JEDEC stamp signifies the unanimous approval from our industry peers for the superior capabilities of the ELP package,” said Greg Phipps, design manager at AIT. “The approval validates AIT's commitment to excellence in technology and customer satisfaction in the packaging industry.”

AIT's patented ELP is a Quad lead-free staggered and in-line multi-row package with metallized terminals along the edges of the bottom surface. The distinctive design makes the leadframe mechanically and thermally robust, eliminating distortions and deformations during the chip attach and wire-bonding process. The package is offered in two- or three-row configurations. Compared to other QFN packages currently available in the market, ELP offers several benefits, including smaller footprint, lower cost and design flexibility for higher I/O count.

“While ELP's exposed pad design enables low tooling costs, its proven high-volume assembly process guarantees a faster time to market, offering customers the competitive

edge in the fast-paced wireless consumer market,” said Phipps. ELP is ideal for creating packages required for smaller, slimmer consumer applications like cell phones, PDAs and other portable devices driving the semiconductor industry.

About Advanced Interconnect Technologies (AIT)

Advanced Interconnect Technologies is a global provider of semiconductor assembly and test services for many of the world’s most successful electronics companies. The company’s turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. AIT has received recognition for its field service and product yields from several of the industry’s leading semiconductor device manufacturers. The company is also ISO 9001:2000, ISO 14001-2004 and ISO/TS16949-2002 certified. With approximately 3,700 employees worldwide, AIT has factory locations in Batam, Indonesia and Sunnyvale, Calif. For more information about the company, its products and services, please visit its website at www.aithome.com.

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